

R&D CLUSTER TOOL SAF



CLUSTER TOOL SAF

Research and development works, feasibility studies and general academic work in the field of thin film technologies

Sample manufacturing aimed at product prototyping for market evaluation of out-of-box technologies



CLUSTER TOOL SAF

SIMPLE

Easy and simple tool control and maintenance

ADJUSTABLE

Customized configuration and setup

FLEXIBLE

Wide spectrum of possible technological processes





TARGET CUSTOMERS

Laboratories engaged or with the intentions of working to carry out research for thin film technologies

Companies already working and possibly with production facilities with a desire or need to develop further the technology and to try to differentiate themselves from others

Universities working or intending to work in the thin film area



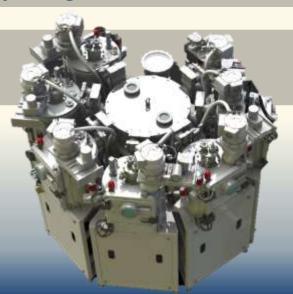
DESIGN ADVANTAGES

The cluster tool is a modular, expandable and flexible system

Each chamber can operate independently due to individual pumping station, control and utility flange

Deposition chambers and deposition sources are interchangeable due **to identical** design of the chambers and utility flanges

All chambers can operate simultaneously





SAF CONFIGURATION

THE CENTRAL CHAMBER IS EQUIPPED WITH 8 FLANGES FOR CHAMBERS OF YOUR CHOICE:

Substrate loading/unloading and pre-treatment

Substrate storage

Deposition process chambers:

Electron beam evaporation

Thermal evaporation

Thermal sublimation

Magnetron sputtering

Other deposition processes





OPTIONS

Residual Gas Analysis/Mass Spectrometry

Plasma Emission Monitoring

Glove box



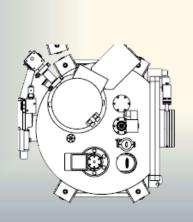
DELIVERY OPTIONS

Any solo process chamber

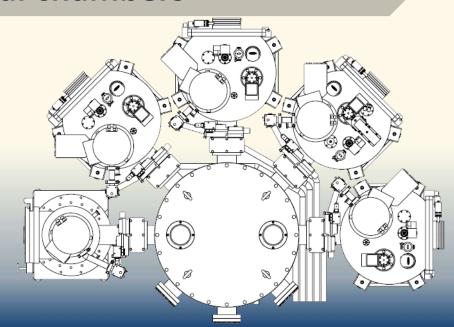
Cluster with the necessary process chambers

Customized arrangement and instrumentation

Additional chambers



OR





TECHNOLOGICAL KEY FEATURES

Various substrates (metal, glass, plastic, ceramic), standard size 50x50x5 mm

Substrate ion pretreatment

Contact and contactless substrate heating/cooling

Deposition of multi-layer coating stacks without tool venting

Uniform coating due to rotatable substrate holder

Debris-free coating due to upward deposition

Base pressure – 10⁻⁷ Torr

Process control

Blanked-off flanges on the process chambers allow attaching customized instrumentation and technological accessories



CENTRAL TRANSFER CHAMBER

TRANSPORTATION OF THE SUBSTRATE



Substrate storage chamber - up to 6 samples

Telescopic robotic arm

8 sealed mount flanges

Detachable top lid

2 view ports

Interior lighting

Pumping system

Vacuum gauges

PREVENTS PROCESS CROSS-CONTAMINATION AND ENSURES SUBSTRATE

TRANSFER WITHOUT VENTING OF THE CHAMBERS



CENTRAL TRANSFER CHAMBER

SAMPLE STORAGE IN VACUUM OR INERT GAS ATMOSPHERE



Two-level sample holder

The amount of samples – 6pcs

Optical sensor of sample presence

CAN BE REPLACED BY ANY PROCESS CHAMBER



STANDARD UNITS FOR EACH DEPOSITION CHAMBER

Quartz resonators (except for the magnetron sputtering chamber)

Rotatable substrate holder

Gas feeding system

Substrate shutter

View port

Interior lighting

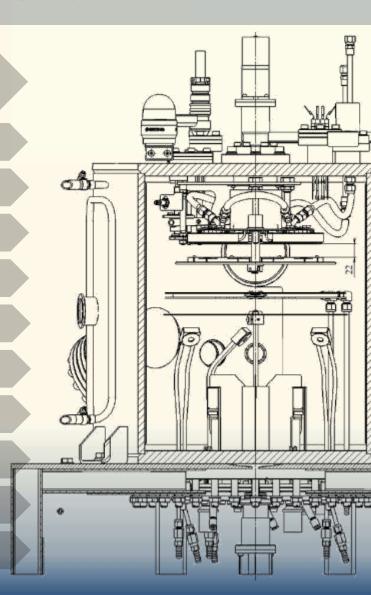
Pumping system

Vacuum gauges

Cooling/ heating water system

Electrical and control system

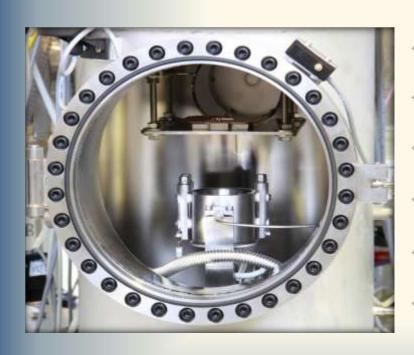
Hinged door





INPUT/OUTPUT CHAMBER, ION PRETREATMENT

SUBSTRATE LOADING/ UNLOADING



Circular source with cold cathode

2 filaments

Process gasses Ar, O₂

Stationary substrate holder

Sensor of substrate presence

Standard chamber equipment

SUBSTRATE PRETREATMENT TO ENHANCE COATING ADHESION AND ENSURE STABILITY OF COATING PROPERTIES



THERMAL EVAPORATION CHAMBER

THERMAL EVAPORATION WITH RESISTIVE ELEMENTS



Crucibles and boats (up to 4 pcs.)

Substrate IR heating device (up to 200° C)

Substrate temperature measurement

Purge gas N₂

Substrate masking

Standard chamber equipment

METAL AND ALLOY COATINGS



THERMAL EVAPORATION CHAMBER

METAL AND ALLOY COATINGS



Semiconductor wafers

Solar cells

Metallized foil

Architectural glass etc.



THERMAL SUBLIMATION CHAMBER

THERMAL SUBLIMATION OF ORGANIC SUBSTANCES



3 thermal sublimation cells

Substrate contact heating/ cooling (-40..+60°C)

Substrate and cells temperature measurement

Purge gas N₂

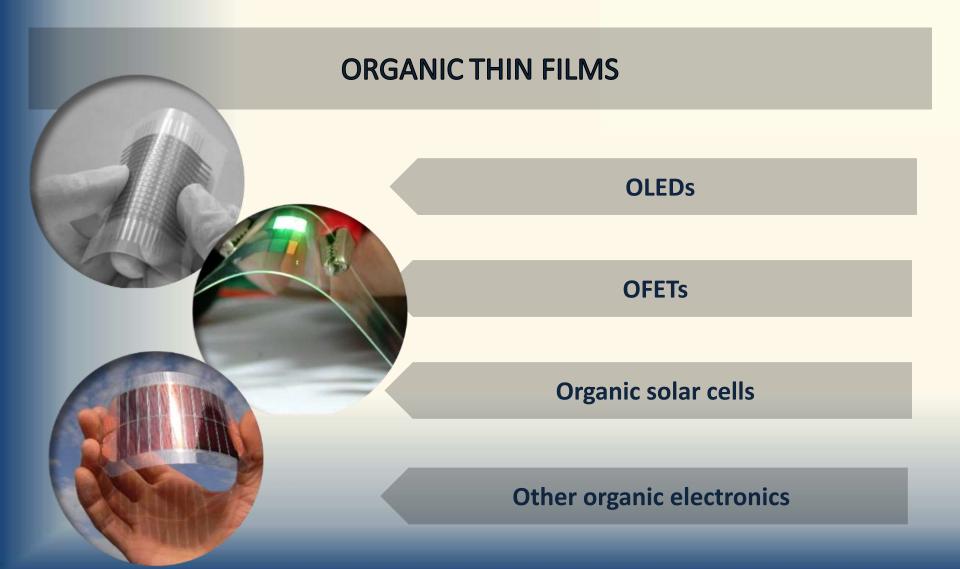
Substrate masking

Standard chamber equipment

OLEDs, ORGANIC PHOTOVOLTAICS, HIGH-PURITY MATERIALS FOR ORGANIC ELECTRONICS



THERMAL SUBLIMATION CHAMBER





MAGNETRON SPUTTERING CHAMBER

MAGNETRON SPUTTERING IN METAL, QUASI-REACTIVE AND REACTIVE MODE



Substrate IR heating up to 400° C

Substrate temperature measurement

3 circular, planar magnetrons

Available DC, pulsed DC, MF and RF power supply

Twin, dual or single combination of magnetrons

METAL, ALLOY, OXIDE, TCO, NITRIDE, CARBIDE, POLYMER, SEMI-CONDUCTOR
AND P-I-N COATINGS



MAGNETRON SPUTTERING CHAMBER

MAGNETRON SPUTTERING IN METAL, QUASI-REACTIVE AND REACTIVE MODE

Individual shutter for each magnetron

Process gasses: Ar, H₂, N₂, O₂

Changeable distance substrate to magnetron sources

Changeable magnetron tilt according to the substrate

Standard chamber equipment



METAL, ALLOY, OXIDE, TCO, NITRIDE, CARBIDE, POLYMER, SEMI-CONDUCTOR
AND P-I-N COATINGS



MAGNETRON SPUTTERING CHAMBER

METAL, ALLOY, OXIDE, TCO, NITRIDE, CARBIDE, POLYMER, SEMI-CONDUCTOR AND P-I-N COATINGS



Solar cells

Flexible circuit boards, electronics

Decorative and protective coatings

Antibacterial coatings

And many other applications



TECHNICAL OUTLINE



Dimensions (LxWxH) – 3 x 3 x 2 m

Weight - 2.8 t

Installed power 50 kW

Cooling water consumption 2.7 m³/h



THE FULLY CUSTOMIZABLE CLUSTER TOOL

THE BEST APPROACH TO NEW MATERIALS FOR DIFFERENT INDUSTRIES





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